

Micropower Voltage Detector

Features

- Ultra-low supply current: 1.75 μA (max.)
- Precision monitoring options of:
 - 1.90V, 2.32V, 2.63V, 2.90V, 2.93V, 3.08V, 4.38V and 4.63V
- Resets microcontroller in a power-loss event
- Active-low V_{OUT} pin:
 - **MCP111** active-low, open-drain
 - **MCP112** active-low, push-pull
- Available in SOT23-3, TO-92, SC-70 and SOT-89-3 packages
- Temperature Range:
 - Extended: -40°C to $+125^{\circ}\text{C}$ (except **MCP1XX-195**)
 - Industrial: -40°C to $+85^{\circ}\text{C}$ (**MCP1XX-195 only**)
- Pb-free devices

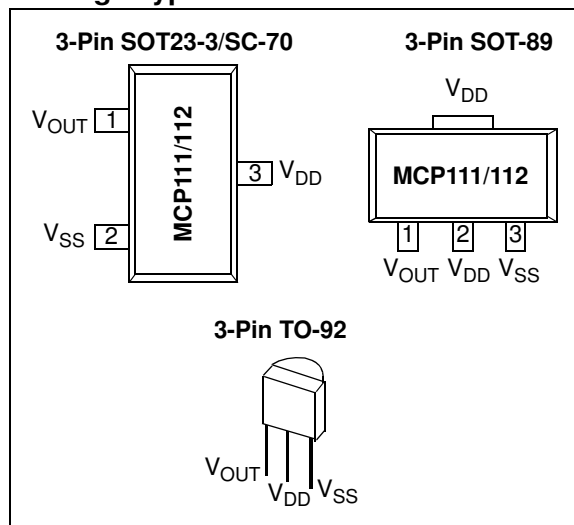
Applications

- Critical Microcontroller and Microprocessor Power-Monitoring Applications
- Computers
- Intelligent Instruments
- Portable Battery-Powered Equipment

Description

The MCP111/112 are voltage-detecting devices designed to keep a microcontroller in reset until the system voltage has stabilized at the appropriate level for reliable system operation. These devices also operate as protection from brown-out conditions when the system supply voltage drops below the specified threshold voltage level. Eight different trip voltages are available.

Package Types



Block Diagram

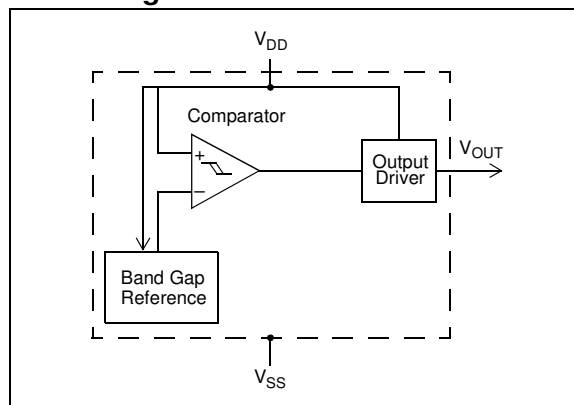


TABLE 1: DEVICE FEATURES

Device	Output		Reset Delay (typ)	Package Pin Out (Pin # 1, 2, 3)	Comment
	Type	Pull-up Resistor			
MCP111	Open-drain	External	No	$V_{\text{OUT}}, V_{\text{SS}}, V_{\text{DD}}$	
MCP112	Push-pull	No	No	$V_{\text{OUT}}, V_{\text{SS}}, V_{\text{DD}}$	
MCP102	Push-pull	No	120 ms	$\overline{\text{RST}}, V_{\text{DD}}, V_{\text{SS}}$	See MCP102/103/121/131 Data Sheet (DS21906)
MCP103	Push-pull	No	120 ms	$V_{\text{SS}}, \overline{\text{RST}}, V_{\text{DD}}$	See MCP102/103/121/131 Data Sheet (DS21906)
MCP121	Open-drain	External	120 ms	$\overline{\text{RST}}, V_{\text{DD}}, V_{\text{SS}}$	See MCP102/103/121/131 Data Sheet (DS21906)
MCP131	Open-Drain	Internal (~95 k Ω)	120 ms	$\overline{\text{RST}}, V_{\text{DD}}, V_{\text{SS}}$	See MCP102/103/121/131 Data Sheet (DS21906)

MCP111/112

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

V_{DD}	7.0V
Input current (V_{DD})	10 mA
Output current (\overline{RST})	10 mA
Rated Rise Time of V_{DD}	100V/ μ s
All inputs and outputs (except \overline{RST}) w.r.t. V_{SS}	-0.6V to ($V_{DD} + 1.0V$)
\overline{RST} output w.r.t. V_{SS}	-0.6V to 13.5V
Storage temperature	-65°C to +150°C
Ambient temp. with power applied	-40°C to +125°C
Maximum Junction temp. with power applied	150°C
ESD protection on all pins	≥ 2 kV

† **Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to 5.5V, $R_{PU} = 100$ k Ω (only **MCP111**), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

Parameters		Sym	Min	Typ	Max	Units	Conditions
Operating Voltage Range		V_{DD}	1.0	—	5.5	V	
Specified V_{DD} Value to V_{OUT} low		V_{DD}	1.0	—		V	$I_{\overline{RST}} = 10 \mu\text{A}$, $V_{\overline{RST}} < 0.2V$
Operating Current		I_{DD}	—	< 1	1.75	μA	
V_{DD} Trip Point	MCP1XX-195	V_{TRIP}	1.872	1.900	1.929	V	$T_A = +25^\circ\text{C}$ (Note 1)
			1.853	1.900	1.948	V	$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (Note 2)
	MCP1XX-240		2.285	2.320	2.355	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.262	2.320	2.378	V	Note 2
	MCP1XX-270		2.591	2.630	2.670	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.564	2.630	2.696	V	Note 2
	MCP1XX-290		2.857	2.900	2.944	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.828	2.900	2.973	V	Note 2
	MCP1XX-300		2.886	2.930	2.974	V	$T_A = +25^\circ\text{C}$ (Note 1)
			2.857	2.930	3.003	V	Note 2
	MCP1XX-315		3.034	3.080	3.126	V	$T_A = +25^\circ\text{C}$ (Note 1)
			3.003	3.080	3.157	V	Note 2
	MCP1XX-450		4.314	4.380	4.446	V	$T_A = +25^\circ\text{C}$ (Note 1)
			4.271	4.380	4.490	V	Note 2
MCP1XX-475	4.561	4.630	4.700	V	$T_A = +25^\circ\text{C}$ (Note 1)		
	4.514	4.630	4.746	V	Note 2		
V_{DD} Trip Point Tempco		T_{TPCO}	—	± 100	—	ppm/ $^\circ\text{C}$	

- Note 1:** Trip point is $\pm 1.5\%$ from typical value.
Note 2: Trip point is $\pm 2.5\%$ from typical value.
3: This specification allows this device to be used in PIC[®] microcontroller applications that require the In-Circuit Serial Programming™ (ICSP™) feature (see device-specific programming specifications for voltage requirements). This specification DOES NOT allow a continuous high voltage to be present on the open-drain output pin (V_{OUT}). The total time that the V_{OUT} pin can be above the maximum device operational voltage (5.5V) is 100 sec. Current into the V_{OUT} pin should be limited to 2 mA. It is recommended that the device operational temperature be maintained between 0°C to 70°C (+25°C preferred). For additional information, please refer to Figure 2-28.
4: This parameter is established by characterization and is not 100% tested.

DC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only MCP111), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.							
Parameters	Sym	Min	Typ	Max	Units	Conditions	
Threshold Hysteresis (min. = 1%, max = 6%)	MCP1XX-195	V_{HYS}	0.019	—	0.114	V	$T_A = +25^\circ\text{C}$
	MCP1XX-240		0.023	—	0.139	V	
	MCP1XX-270		0.026	—	0.158	V	
	MCP1XX-290		0.029	—	0.174	V	
	MCP1XX-300		0.029	—	0.176	V	
	MCP1XX-315		0.031	—	0.185	V	
	MCP1XX-450		0.044	—	0.263	V	
	MCP1XX-475		0.046	—	0.278	V	
V_{OUT} Low-level Output Voltage	V_{OL}	—	—	0.4	V	$I_{OL} = 500\text{ }\mu\text{A}$, $V_{DD} = V_{TRIP(MIN)}$	
V_{OUT} High-level Output Voltage	V_{OH}	$V_{DD} - 0.6$	—	—	V	$I_{OH} = 1\text{ mA}$, For only MCP112 (push-pull output)	
Open-drain High Voltage on Output	V_{ODH}	—	—	13.5 ⁽³⁾	V	MCP111 only, $V_{DD} = 3.0V$, Time voltage > 5.5V applied $\leq 100s$, current into pin limited to 2 mA, $+25^\circ\text{C}$ operation recommended Note 3, Note 4	
Open-drain Output Leakage Current (MCP111 only)	I_{OD}	—	0.1	—	μA		

Note 1: Trip point is $\pm 1.5\%$ from typical value.

Note 2: Trip point is $\pm 2.5\%$ from typical value.

Note 3: This specification allows this device to be used in PIC[®] microcontroller applications that require the In-Circuit Serial Programming™ (ICSP™) feature (see device-specific programming specifications for voltage requirements). This specification DOES NOT allow a continuous high voltage to be present on the open-drain output pin (V_{OUT}). The total time that the V_{OUT} pin can be above the maximum device operational voltage (5.5V) is 100 sec. Current into the V_{OUT} pin should be limited to 2 mA. It is recommended that the device operational temperature be maintained between 0°C to 70°C ($+25^\circ\text{C}$ preferred). For additional information, please refer to Figure 2-28.

Note 4: This parameter is established by characterization and is not 100% tested.

MCP111/112

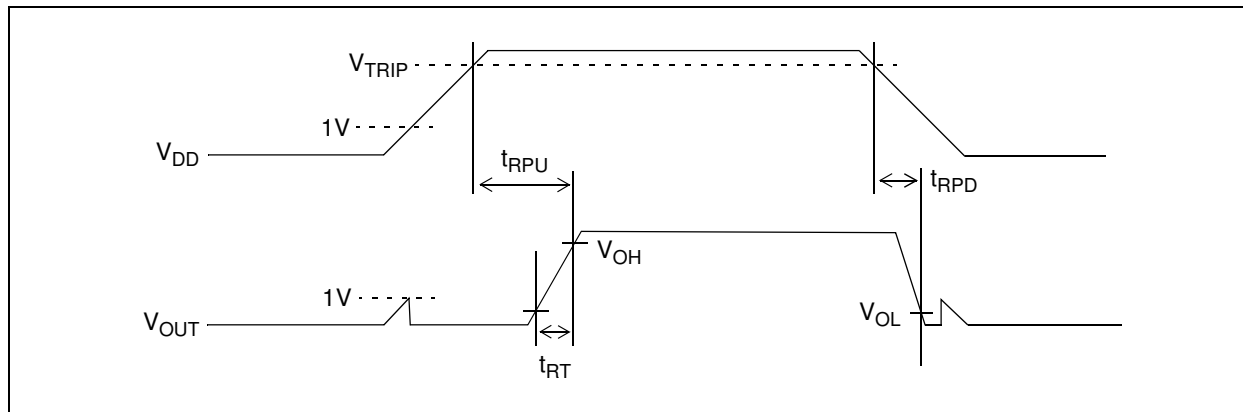


FIGURE 1-1: Timing Diagram.

AC CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only **MCP111**), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

Parameters	Sym	Min	Typ	Max	Units	Conditions
V_{DD} Detect to V_{OUT} Inactive	t_{RPU}	—	90	—	μs	Figure 1-1 and $C_L = 50\text{ pF}$ (Note 1)
V_{DD} Detect to V_{OUT} Active	t_{RPD}	—	130	—	μs	V_{DD} ramped from $V_{TRIP(MAX)} + 250\text{ mV}$ down to $V_{TRIP(MIN)} - 250\text{ mV}$, per Figure 1-1, $C_L = 50\text{ pF}$ (Note 1)
V_{OUT} Rise Time After V_{OUT} Active	t_{RT}	—	5	—	μs	For V_{OUT} 10% to 90% of final value per Figure 1-1, $C_L = 50\text{ pF}$ (Note 1)

Note 1: These parameters are for design guidance only and are not 100% tested.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only **MCP111**), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Specified Temperature Range	T_A	-40	—	+85	$^\circ\text{C}$	MCP1XX-195
Specified Temperature Range	T_A	-40	—	+125	$^\circ\text{C}$	Except MCP1XX-195
Maximum Junction Temperature	T_J	—	—	+150	$^\circ\text{C}$	
Storage Temperature Range	T_A	-65	—	+150	$^\circ\text{C}$	
Package Thermal Resistances						
Thermal Resistance, 3L-SOT23	θ_{JA}	—	336	—	$^\circ\text{C/W}$	
Thermal Resistance, 3L-SC-70	θ_{JA}	—	340	—	$^\circ\text{C/W}$	
Thermal Resistance, 3L-TO-92	θ_{JA}	—	131.9	—	$^\circ\text{C/W}$	
Thermal Resistance, 3L-SOT-89	θ_{JA}	—	110	—	$^\circ\text{C/W}$	

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only **MCP111**; see **Figure 4-1**), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

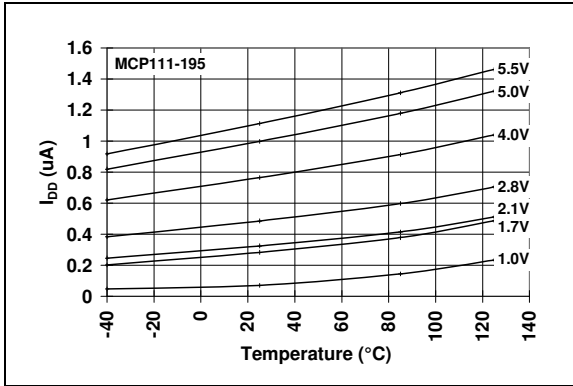


FIGURE 2-1: I_{DD} vs. Temperature (MCP111-195).

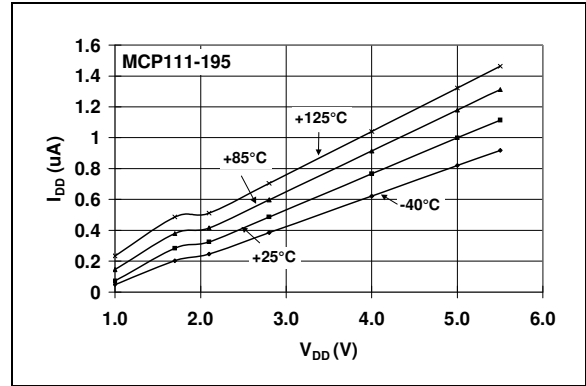


FIGURE 2-4: I_{DD} vs. V_{DD} (MCP111-195).

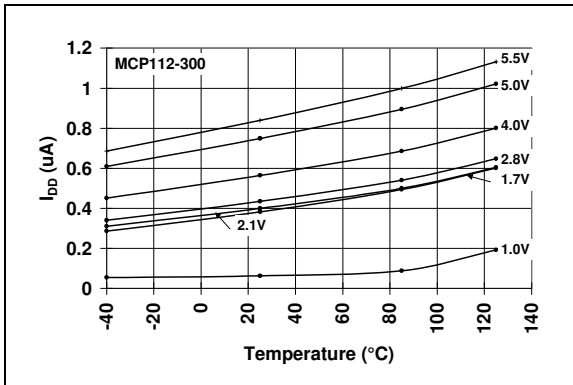


FIGURE 2-2: I_{DD} vs. Temperature (MCP112-300).

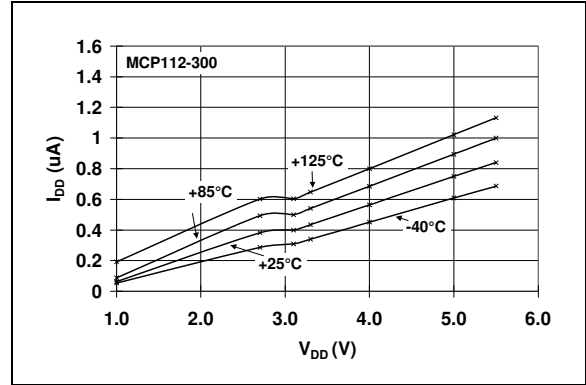


FIGURE 2-5: I_{DD} vs. V_{DD} (MCP112-300).

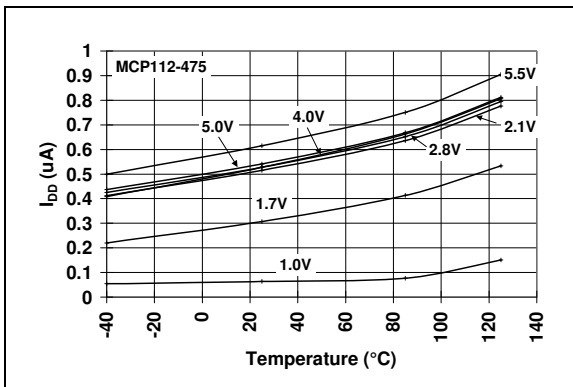


FIGURE 2-3: I_{DD} vs. Temperature (MCP112-475).

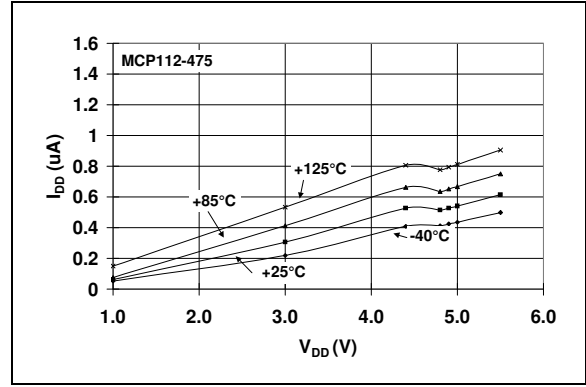


FIGURE 2-6: I_{DD} vs. V_{DD} (MCP112-475).

MCP111/112

Note: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only **MCP111**); see **Figure 4-1**), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

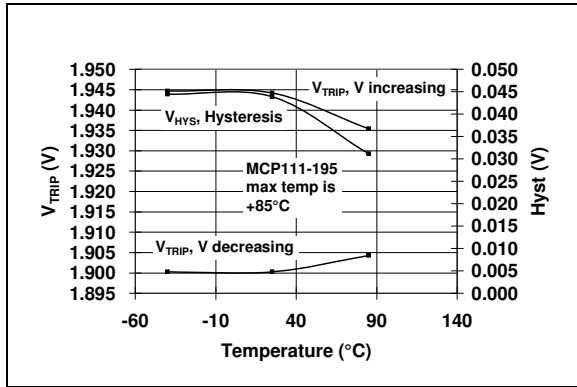


FIGURE 2-7: V_{TRIP} and V_{HYST} vs. Temperature (**MCP111-195**).

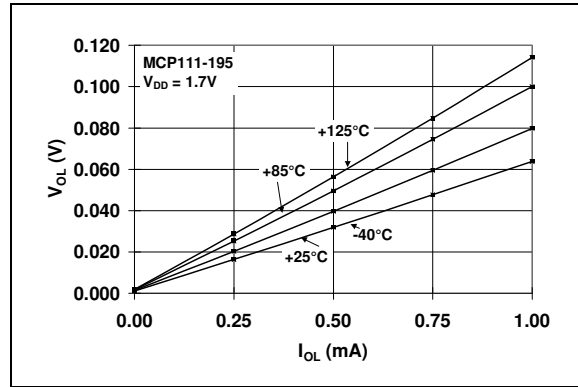


FIGURE 2-10: V_{OL} vs. I_{OL} (**MCP111-195** @ $V_{DD} = 1.7V$).

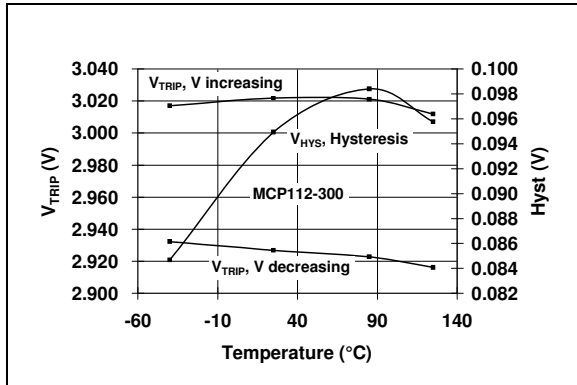


FIGURE 2-8: V_{TRIP} and V_{HYST} vs. Temperature (**MCP112-300**).

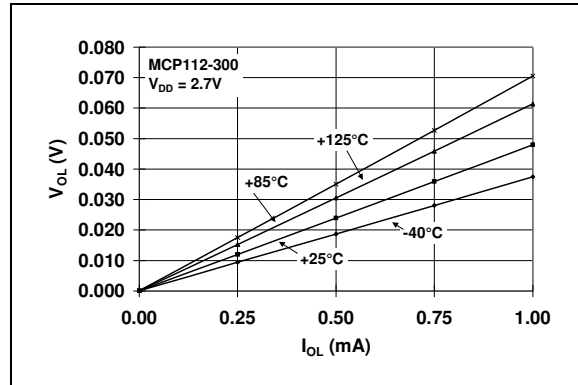


FIGURE 2-11: V_{OL} vs. I_{OL} (**MCP112-300** @ $V_{DD} = 2.7V$).

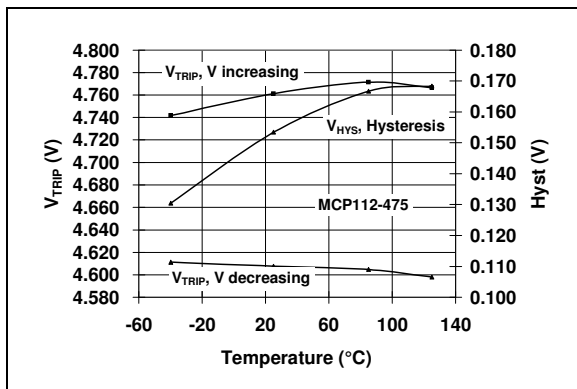


FIGURE 2-9: V_{TRIP} and V_{HYST} vs. Temperature (**MCP112-475**).

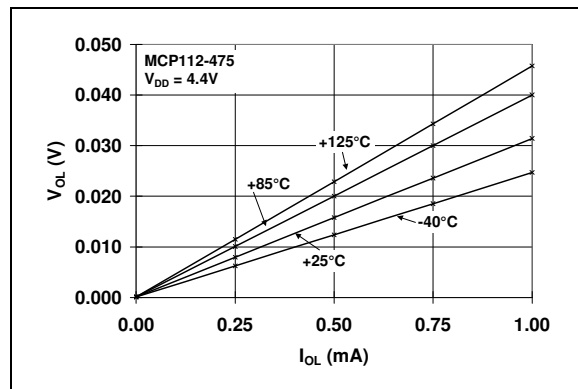


FIGURE 2-12: V_{OL} vs. I_{OL} (**MCP112-475** @ $V_{DD} = 4.4V$).

Note: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only MCP111; see Figure 4-1), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

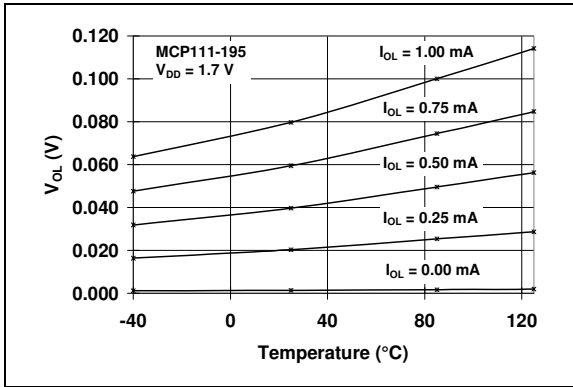


FIGURE 2-13: V_{OL} vs. Temperature (MCP111-195 @ $V_{DD} = 1.7V$).

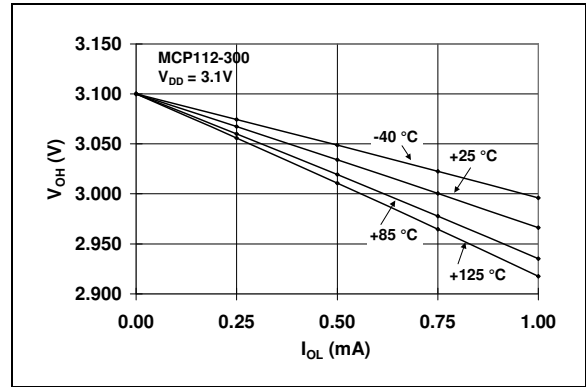


FIGURE 2-16: V_{OH} vs. I_{OH} (MCP112-300 @ $V_{DD} = 3.1V$).

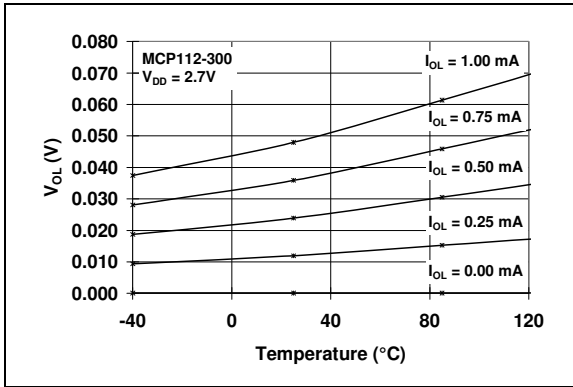


FIGURE 2-14: V_{OL} vs. Temperature (MCP112-300 @ $V_{DD} = 2.7V$).

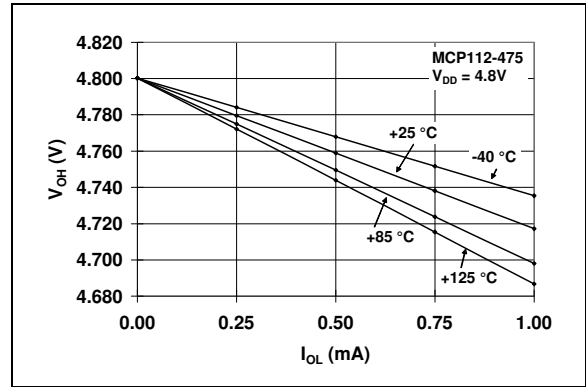


FIGURE 2-17: V_{OH} vs. I_{OH} (MCP112-475 @ $V_{DD} = 4.8V$).

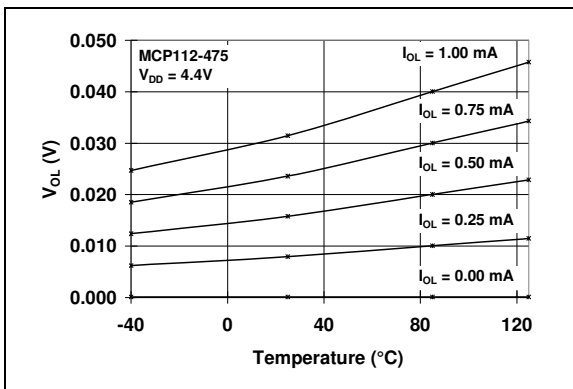


FIGURE 2-15: V_{OL} vs. Temperature (MCP112-475 @ $V_{DD} = 4.4V$).

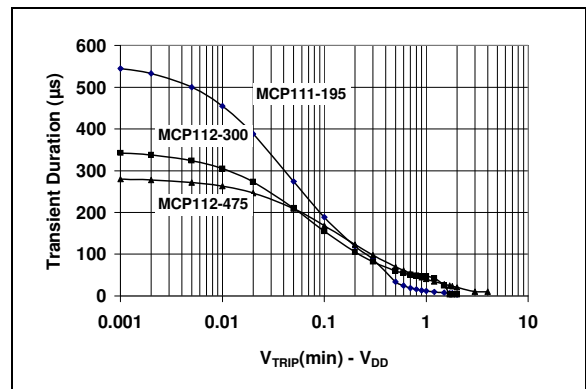


FIGURE 2-18: Typical Transient Response (25 °C).

MCP111/112

Note: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only MCP111; see Figure 4-1), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

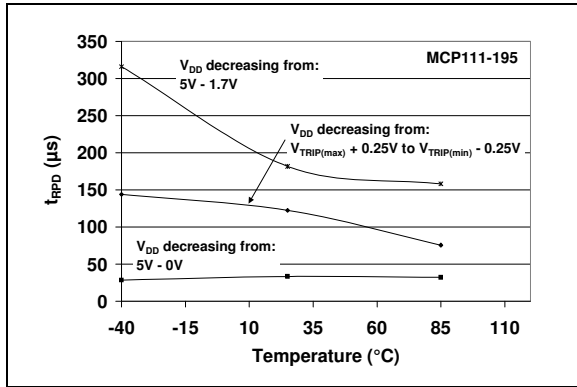


FIGURE 2-19: t_{RPD} vs. Temperature (MCP111-195).

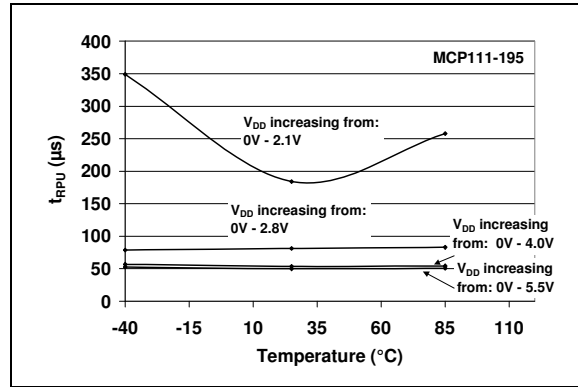


FIGURE 2-22: t_{RPU} vs. Temperature (MCP111-195).

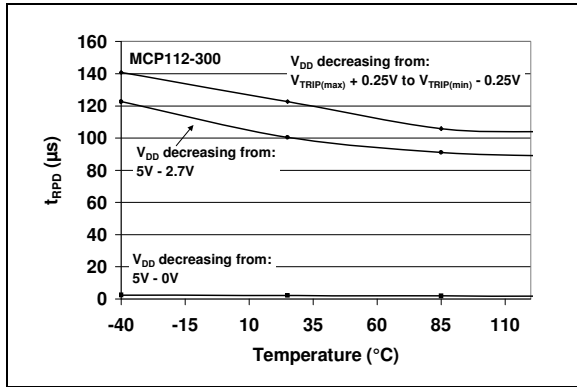


FIGURE 2-20: t_{RPD} vs. Temperature (MCP112-300).

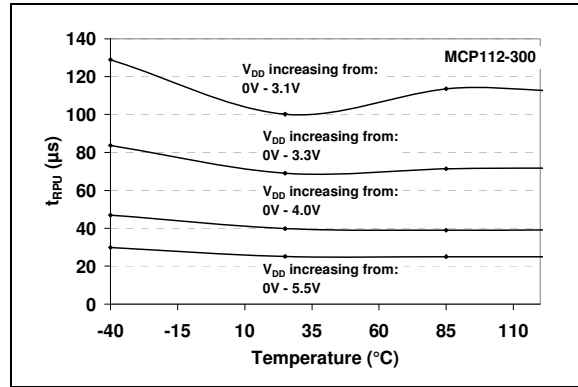


FIGURE 2-23: t_{RPU} vs. Temperature (MCP112-300).

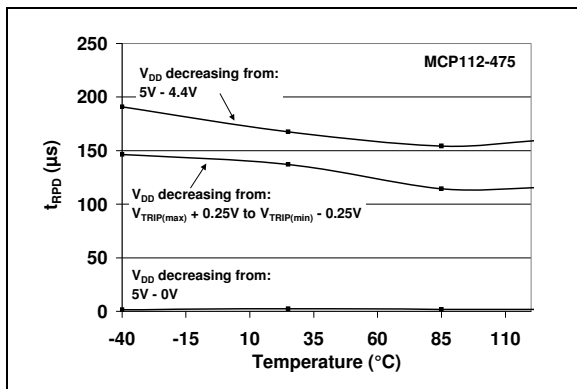


FIGURE 2-21: t_{RPD} vs. Temperature (MCP112-475).

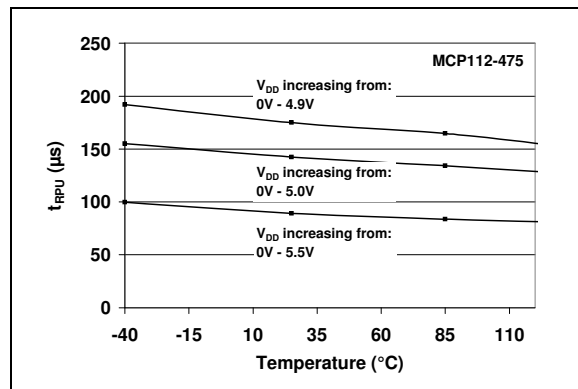


FIGURE 2-24: t_{RPU} vs. Temperature (MCP112-475).

Note: Unless otherwise indicated, all limits are specified for $V_{DD} = 1V$ to $5.5V$, $R_{PU} = 100\text{ k}\Omega$ (only MCP111; see Figure 4-1), $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$.

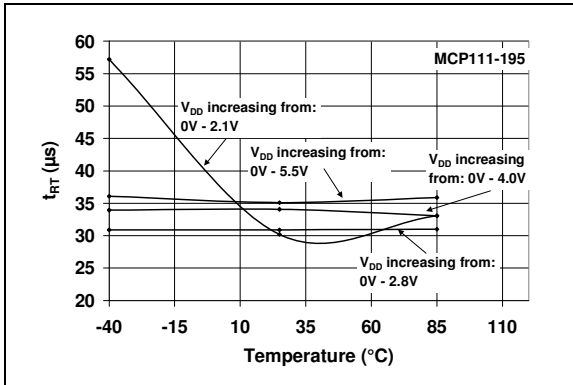


FIGURE 2-25: t_{RT} vs. Temperature (MCP111-195).

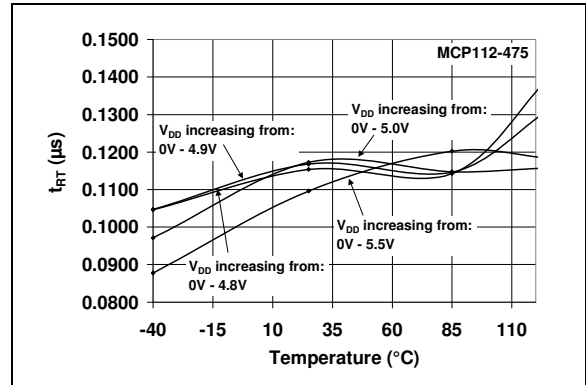


FIGURE 2-27: t_{RT} vs. Temperature (MCP112-475).

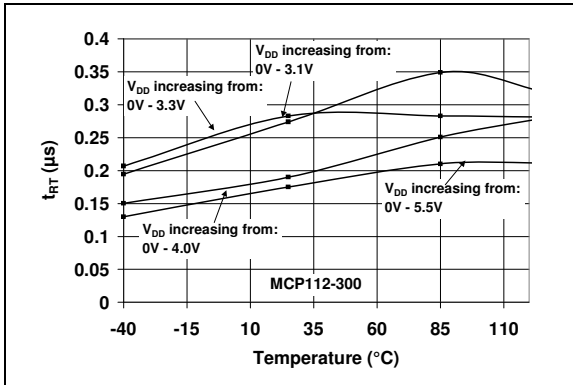


FIGURE 2-26: t_{RT} vs. Temperature (MCP112-300).

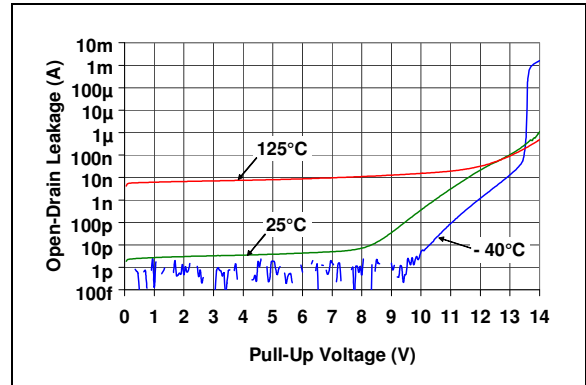


FIGURE 2-28: Open-Drain Leakage Current vs. Voltage Applied to V_{OUT} Pin (MCP111-195).

MCP111/112

3.0 PIN DESCRIPTION

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

Pin No.			Symbol	Function
SOT-23-3 SC-70	SOT-89-3	T0-92		
1	1	1	V_{OUT}	Output State V_{DD} Falling: $H = V_{DD} > V_{TRIP}$ $L = V_{DD} < V_{TRIP}$ V_{DD} Rising: $H = V_{DD} > V_{TRIP} + V_{HYS}$ $L = V_{DD} < V_{TRIP} + V_{HYS}$
2	2	3	V_{SS}	Ground reference
3	3	2	V_{DD}	Positive power supply
—	4	—	V_{DD}	Positive power supply

4.0 APPLICATION INFORMATION

For many of today's microcontroller applications, care must be taken to prevent low-power conditions that can cause many different system problems. The most common causes are brown-out conditions, where the system supply drops below the operating level momentarily. The second most common cause is when a slowly decaying power supply causes the microcontroller to begin executing instructions without sufficient voltage to sustain SRAM, thus producing indeterminate results. Figure 4-1 shows a typical application circuit.

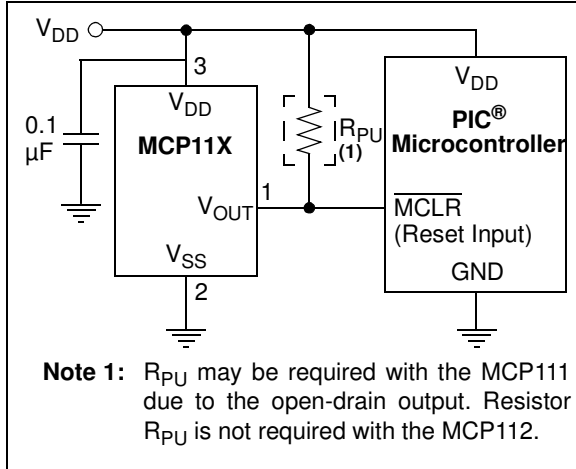


FIGURE 4-1: Typical Application Circuit.

4.1 V_{TRIP} Operation

The voltage trip point (V_{TRIP}) is determined on the falling edge of V_{DD} . The actual voltage trip point (V_{TRIPAC}) will be between the minimum trip point ($V_{TRIPMIN}$) and the maximum trip point ($V_{TRIPMAX}$). There is a hysteresis on this trip point to remove any "jitter" that would occur on the V_{OUT} pin when the device V_{DD} is at the trip point.

Figure 4-2 shows the state of the V_{OUT} pin as determined by the V_{DD} voltage. The V_{TRIP} specification is for falling V_{DD} voltages. When the V_{DD} voltage is rising, the V_{OUT} pin will not be driven high until V_{DD} is at $V_{TRIP} + V_{HYS}$.

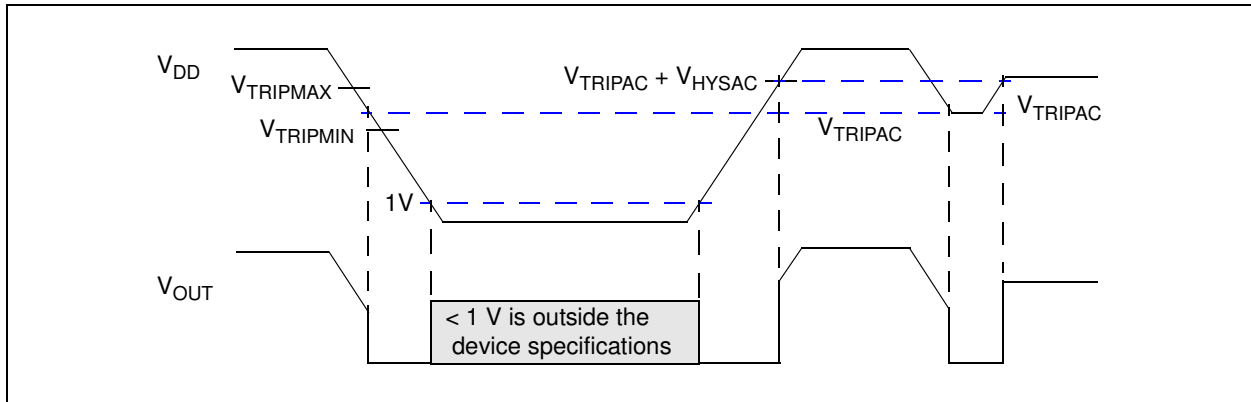


FIGURE 4-2: V_{OUT} Operation as Determined by the V_{TRIP} and V_{HYS} .

MCP111/112

4.2 Negative Going V_{DD} Transients

The minimum pulse width (time) required to cause a reset may be an important criteria in the implementation of a Power-on Reset (POR) circuit. This time is referred to as transient duration, defined as the amount of time needed for these supervisory devices to respond to a drop in V_{DD} . The transient duration time is dependant on the magnitude of $V_{TRIP} - V_{DD}$. Generally speaking, the transient duration decreases with increases in $V_{TRIP} - V_{DD}$.

Figure 4-3 shows a typical transient duration vs. reset comparator overdrive for which the MCP111/112 will not generate a reset pulse. It shows that the farther below the trip point the transient pulse goes, the duration of the pulse required to cause a reset gets shorter. Figure 2-18 shows the transient response characteristics for the MCP111/112.

A 0.1 μF bypass capacitor, mounted as close as possible to the V_{DD} pin, provides additional transient immunity (refer to Figure 4-1).

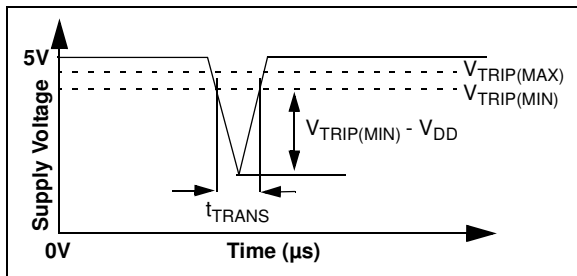


FIGURE 4-3: Example of Typical Transient Duration Waveform.

4.3 Effect of Temperature on Time-out Period (t_{RPU})

The time-out period (t_{RPU}) determines how long the device remains in the reset condition. This is affected by both V_{DD} and temperature. The graph shown in Figures 2-22, 2-23 and 2-24 show the typical response for different V_{DD} values and temperatures.

4.4 Using in PIC[®] Microcontroller ICSP[™] Applications (MCP111 only)

Figure 4-4 shows the typical application circuit for using the MCP111 for voltage supervisory function when the PIC microcontroller will be programmed via the In-Circuit Serial Programming[™] (ICSP) feature. Additional information is available in TB087, "Using Voltage Supervisors with PIC[®] Microcontroller Systems which Implement In-Circuit Serial Programming[™]", DS91087.

Note: It is recommended that the current into the $\overline{\text{RST}}$ pin be current limited by a 1 k Ω resistor.

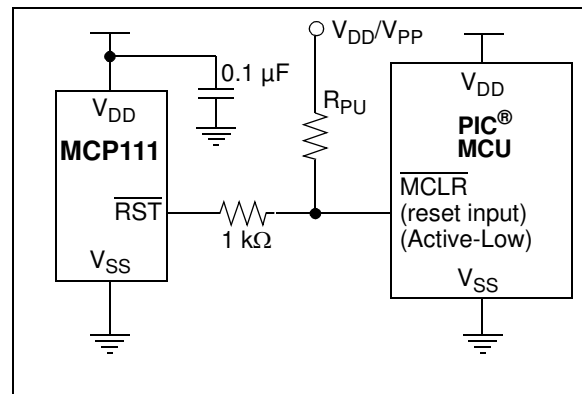
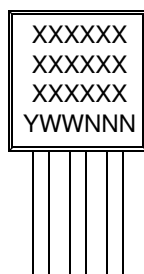


FIGURE 4-4: Typical Application Circuit for PIC[®] Microcontroller with the ICSP[™] feature.

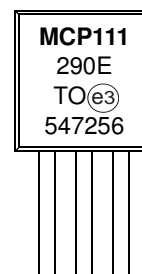
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

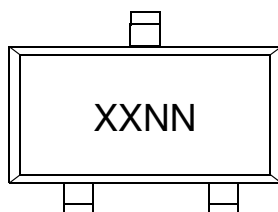
3-Lead TO-92



Example:



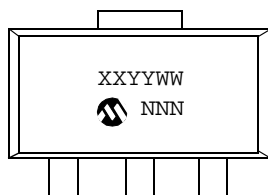
3-Pin SOT-23



Example:

Part Number	SOT-23	Part Number	SOT-23
MCP111T-195I/TT	MPNN	MCP112T-195I/TT	MRNN
MCP111T-240ETT	MQNN	MCP112T-240ETT	MSNN
MCP111T-270E/TT	MGNN	MCP112T-270E/TT	MANN
MCP111T-290E/TT	NHNN	MCP112T-290E/TT	MBNN
MCP111T-300E/TT	MJNN	MCP112T-300E/TT	MCNN
MCP111T-315E/TT	MKNN	MCP112T-315E/TT	MDNN
MCP111T-450E/TT	MLNN	MCP112T-450E/TT	MENN
MCP111T-475E/TT	MMNN	MCP112T-475E/TT	MFNN

3-Pin SOT-89



Example:

Part Number	SOT-89	Part Number	SOT-89
MCP111T-195I/MB	MP	MCP112T-195I/MB	MR
MCP111T-240EMB	MQ	MCP112T-240EMB	MS
MCP111T-270E/MB	MG	MCP112T-270E/MB	MA
MCP111T-290E/MB	NH	MCP112T-290E/MB	MB
MCP111T-300E/MB	MJ	MCP112T-300E/MB	MC
MCP111T-315E/MB	MK	MCP112T-315E/MB	MD
MCP111T-450E/MB	ML	MCP112T-450E/MB	ME
MCP111T-475E/MB	MM	MCP112T-475E/MB	MF

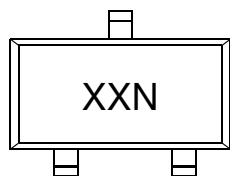
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	ⓔ3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (ⓔ3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

MCP111/112

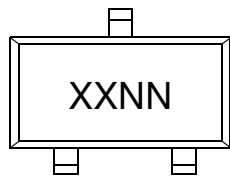
Package Marking Information (Continued)

3-Pin SC-70



Top Side

OR



Top Side

Example:

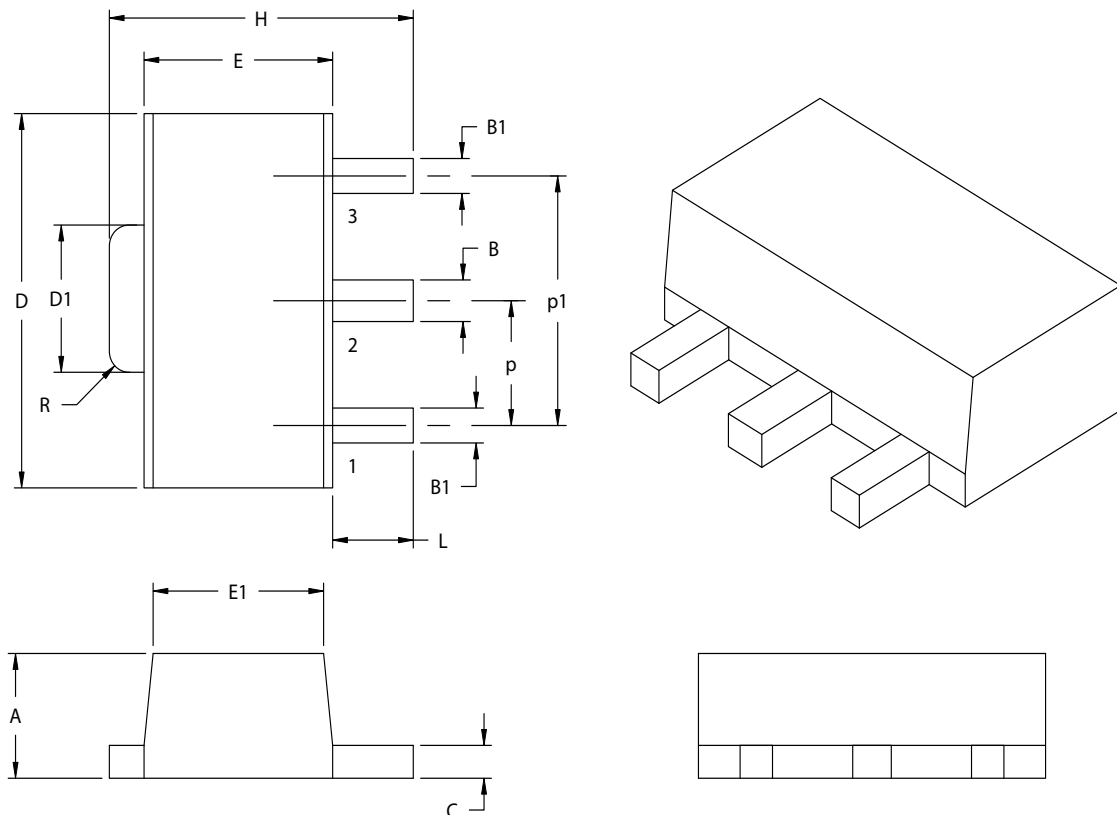
Part Number	SC-70	Part Number	SC-70
MCP111T-195I/LB	EPN	MCP112T-195I/LB	ERN
MCP111T-240E/LB	EQN	MCP112T-240E/LB	ESN
MCP111T-270E/LB	EGN	MCP112T-270E/LB	EAN
MCP111T-290E/LB	EHN	MCP112T-290E/LB	EBN
MCP111T-300E/LB	EJN	MCP112T-300E/LB	ECN
MCP111T-315E/LB	EKN	MCP112T-315E/LB	EDN
MCP111T-450E/LB	ELN	MCP112T-450E/LB	EEN
MCP111T-475E/LB	EMN	MCP112T-475E/LB	EFN

Example:

Part Number	SC-70	Part Number	SC-70
MCP111T-195I/LB	EPNN	MCP112T-195I/LB	ERNN
MCP111T-240E/LB	EQNN	MCP112T-240E/LB	ESNN
MCP111T-270E/LB	EGNN	MCP112T-270E/LB	EANN
MCP111T-290E/LB	EHNN	MCP112T-290E/LB	EBNN
MCP111T-300E/LB	EJNN	MCP112T-300E/LB	ECNN
MCP111T-315E/LB	EKNN	MCP112T-315E/LB	EDNN
MCP111T-450E/LB	ELNN	MCP112T-450E/LB	EENN
MCP111T-475E/LB	EMNN	MCP112T-475E/LB	EFNN

3-Lead Plastic Small Outline Transistor (MB) (SOT89)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		MILLIMETERS*	
		MIN	MAX	MIN	MAX
Pitch	p	.059 BSC		1.50 BSC	
Outside lead pitch (basic)	p1	.118 BSC		3.00 BSC	
Overall Height	A	.055	.063	1.40	1.60
Overall Width	H	.155	.167	3.94	4.25
Molded Package Width at Base	E	.090	.102	2.29	2.60
Molded Package Width at Top	E1	.084	.090	2.13	2.29
Overall Length	D	.173	.181	4.40	4.60
Tab Length	D1	.064	.072	1.62	1.83
Tab Corner Radii	R	.010		0.254	
Foot Length	L	.035	.047	0.89	1.20
Lead Thickness	c	.014	.017	0.35	0.44
Lead 2 Width	B	.017	.022	0.43	0.56
Leads 1 & 3 Width	B1	.014	.019	0.36	0.48

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold or flash protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: TO-243

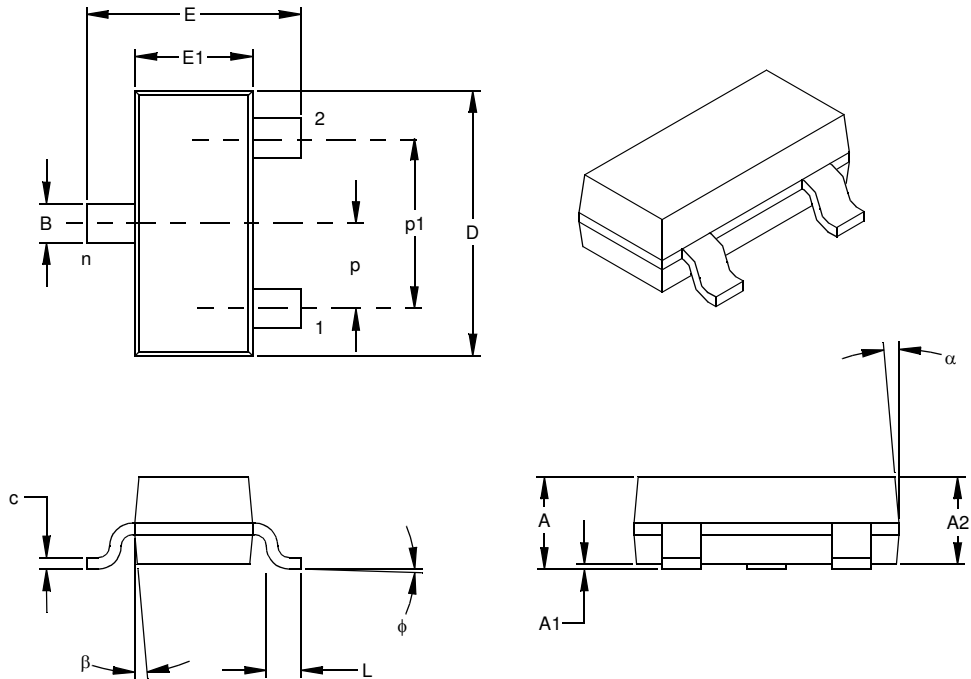
Drawing No. C04-29

Revised 07-24-03

MCP111/112

3-Lead Plastic Small Outline Transistor (TT) (SOT-23)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.038			0.96	
Outside lead pitch (basic)	p1		.076			1.92	
Overall Height	A	.035	.040	.044	0.89	1.01	1.12
Molded Package Thickness	A2	.035	.037	.040	0.88	0.95	1.02
Standoff §	A1	.000	.002	.004	0.01	0.06	0.10
Overall Width	E	.083	.093	.104	2.10	2.37	2.64
Molded Package Width	E1	.047	.051	.055	1.20	1.30	1.40
Overall Length	D	.110	.115	.120	2.80	2.92	3.04
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.007	0.09	0.14	0.18
Lead Width	B	.015	.017	.020	0.37	0.44	0.51
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

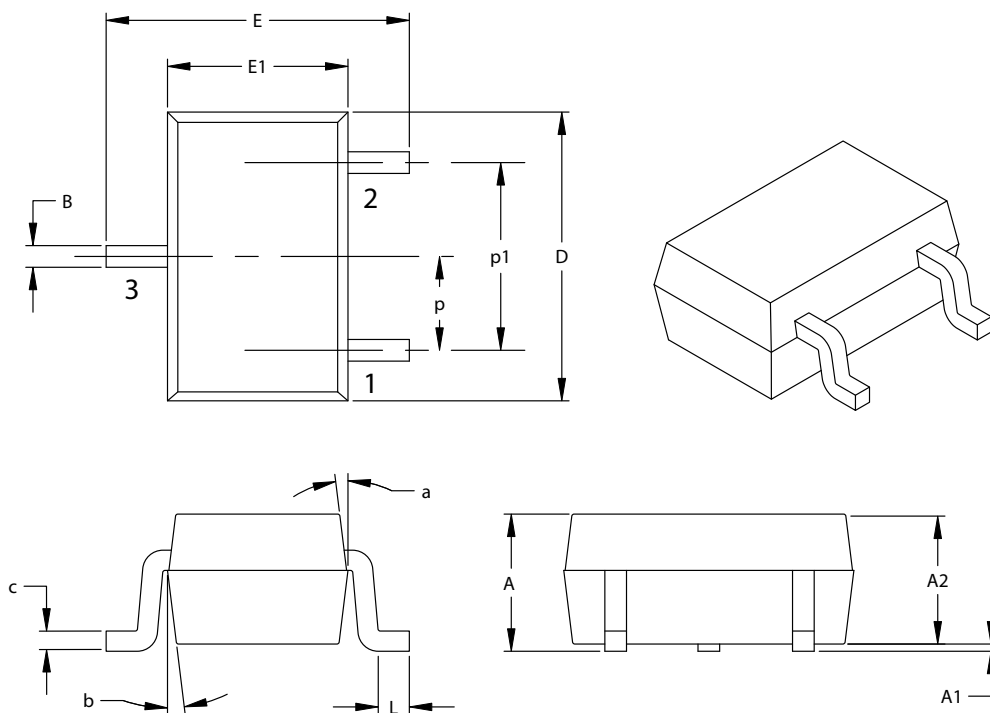
.010" (0.254mm) per side.

JEDEC Equivalent: TO-236

Drawing No. C04-104

3-Lead Plastic Small Outline Transistor (LB) (SC-70)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES		MILLIMETERS*	
		MIN	MAX	MIN	MAX
Number of Pins		3		3	
Pitch	P	.026 BSC.		0.65 BSC.	
Outside lead pitch (basic)	p1	.051 BSC.		1.30 BSC.	
Overall Height	A	.031	.043	0.80	1.10
Molded Package Thickness	A2	.031	.039	0.80	1.00
Standoff	A1	.000	.0004	0.00	.010
Overall Width	E	.071	.094	1.80	2.40
Molded Package Width	E1	.045	.053	1.15	1.35
Overall Length	D	.071	.089	1.80	2.25
Foot Length	L	.004	.016	0.10	0.41
Lead Thickness	c	.003	.010	0.08	0.25
Lead Width	B	.006	.016	0.15	0.40
Mold Draft Angle Top	a	8°	12°	8°	12°
Mold Draft Angle Bottom	b	8°	12°	8°	12°

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

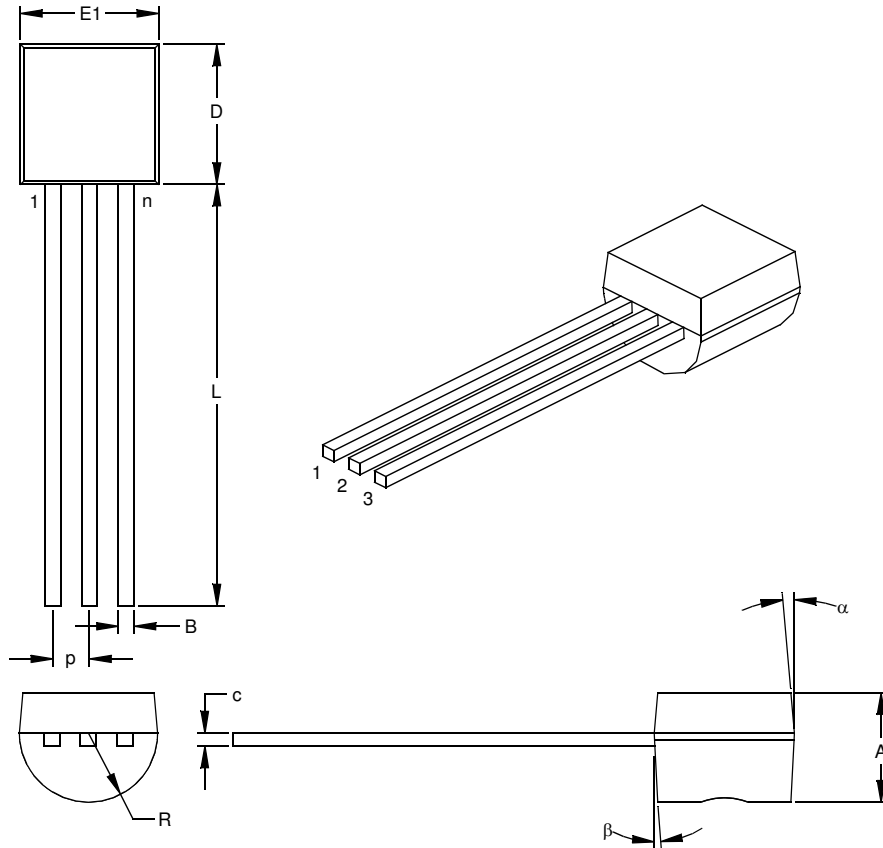
JEITA (EIAJ) Equivalent: SC70

Drawing No. C04-104

MCP111/112

3-Lead Plastic Transistor Outline (TO) (TO-92)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.050			1.27	
Bottom to Package Flat	A	.130	.143	.155	3.30	3.62	3.94
Overall Width	E1	.175	.186	.195	4.45	4.71	4.95
Overall Length	D	.170	.183	.195	4.32	4.64	4.95
Molded Package Radius	R	.085	.090	.095	2.16	2.29	2.41
Tip to Seating Plane	L	.500	.555	.610	12.70	14.10	15.49
Lead Thickness	c	.014	.017	.020	0.36	0.43	0.51
Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Mold Draft Angle Top	α	4	5	6	4	5	6
Mold Draft Angle Bottom	β	2	3	4	2	3	4

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: TO-92

Drawing No. C04-101

5.2 Product Tape and Reel Specifications

FIGURE 5-1: EMBOSSED CARRIER DIMENSIONS (8, 12, 16 AND 24 MM TAPE ONLY)

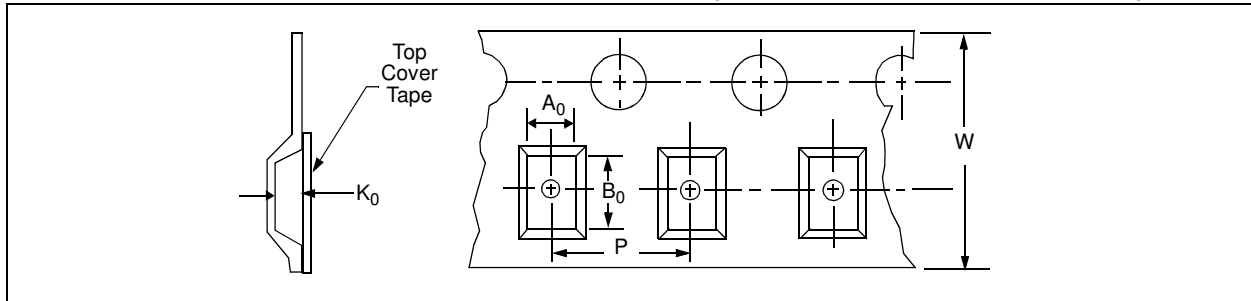
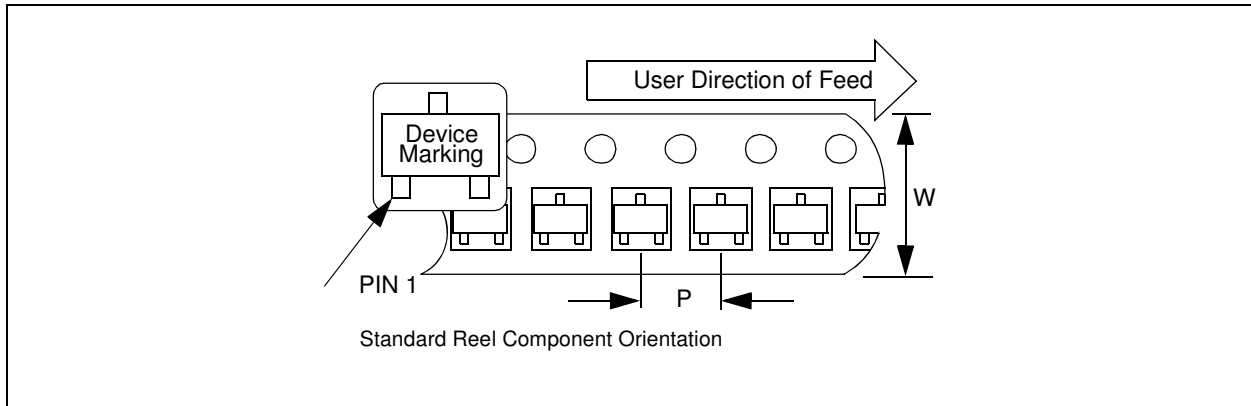


TABLE 1: CARRIER TAPE/CAVITY DIMENSIONS

Case Outline	Package Type		Carrier Dimensions		Cavity Dimensions			Output Quantity Units	Reel Diameter in mm
			W mm	P mm	A0 mm	B0 mm	K0 mm		
TT	SOT-23B	3L	8	4	3.15	2.77	1.22	3000	180
LB	SC-70	3L	8	4	2.4	2.4	1.19	3000	180

FIGURE 5-2: 3-LEAD SOT-23/SC70 DEVICE TAPE AND REEL SPECIFICATIONS



MCP111/112

FIGURE 5-3: TO-92 DEVICES

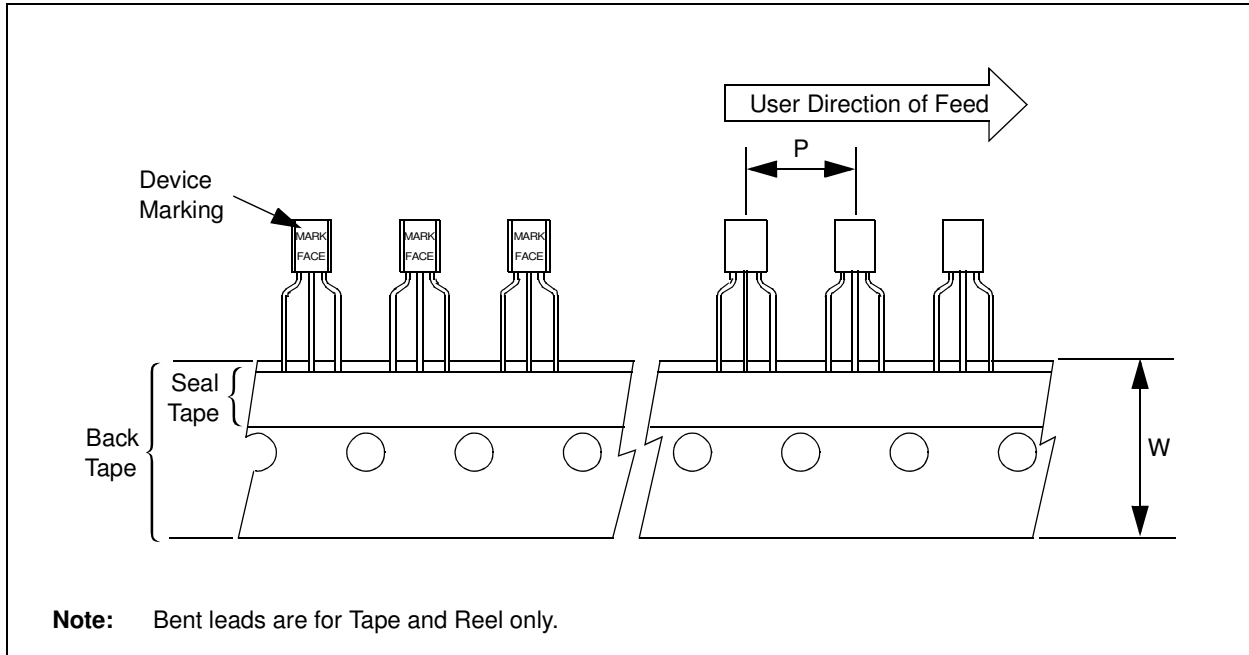
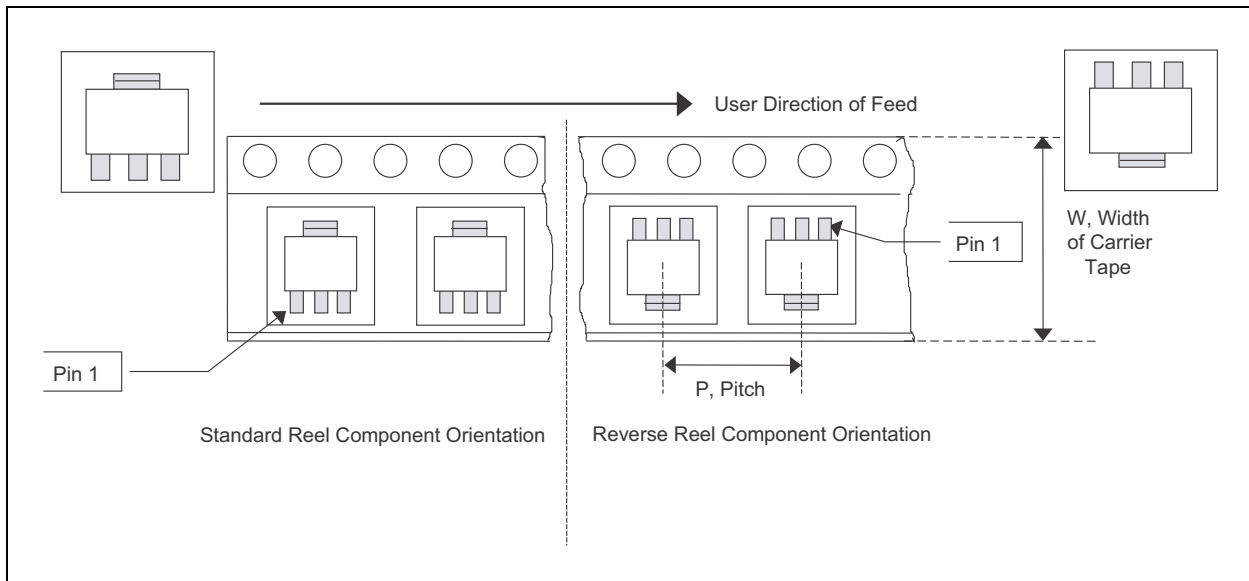


FIGURE 5-4: SOT-89 DEVICES



APPENDIX A: REVISION HISTORY

Revision E (January 2013)

- Added a note to each package outline drawing.

Revision D (June 2005)

1. Added SOT-89-3 package information throughout.

Revision C (March 2005)

The following is the list of modifications:

1. Added **Section 4.4 “Using in PIC® Microcontroller ICSP™ Applications (MCP111 only)”** on using the MCP111 in PIC microcontroller ICSP applications.
2. Added V_{ODH} specifications in **Section 1.0 “Electrical Characteristics”** (for ICSP applications).
3. Added Figure 2-28.
4. Added devices features table to page 1.
5. Updated SC-70 package markings and added Pb-free marking information to **Section 5.0 “Packaging information”**.
6. Added **Appendix A: “Revision History”**.

Revision B (August 2004)

1. Corrected package marking information in **Section 5.0 “Packaging information”**

Revision A (May 2004)

- Original Release of this Document.

MCP111/112

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>XXX</u>	<u>X</u>	<u>XX</u>
Device	Tape/Reel Option	Monitoring Options	Temperature Range	Package
Device:				
		MCP111: MicroPower Voltage Detector, open-drain		
		MCP111T: MicroPower Voltage Detector, open-drain (Tape and Reel)		
		MCP112: MicroPower Voltage Detector, push-pull		
		MCP112T: MicroPower Voltage Detector, push-pull (Tape and Reel)		
Monitoring Options:		195 = 1.90V		
		240 = 2.32V		
		270 = 2.63V		
		290 = 2.90V		
		300 = 2.93V		
		315 = 3.08V		
		450 = 4.38V		
		475 = 4.63V		
Temperature Range:			I = -40°C to +85°C (MCP11X-195 only)	
			E = -40°C to +125°C (Except MCP11X-195 only)	
Package:				LB = SC-70, 3-lead
				MB = SOT-89, 3-lead
				TO = TO-92, 3-lead
				TT = SOT-23B, 3-lead
Examples:				
a)	MCP111T-195I/TT:	Tape and Reel, 1.95V option, open-drain, -40°C to +85°C, SOT-23B package.		
b)	MCP111T-315E/LB:	Tape and Reel, 3.15V option, open-drain, -40°C to +125°C, SC-70-3 package.		
c)	MCP111-300E/TO:	3.00V option, open-drain, -40°C to +125°C, TO-92-3 package.		
d)	MCP111-315E/MB:	3.15V option, open-drain, -40°C to +125°C, SOT-89-3 package.		
a)	MCP112T-290E/TT:	Tape and Reel, 2.90V option, push-pull, -40°C to +125°C, SOT-23B-3 package.		
b)	MCP112T-475E/LB:	Tape and Reel, 4.75V option, push-pull, -40°C to +125°C, SC-70-3 package.		
c)	MCP112-450E/TO:	4.5V option, push-pull, -40°C to +125°C, TO-92-3 package.		
d)	MCP112-315E/MB:	3.15V option, push-pull, -40°C to +125°C, SOT-89-3 package.		

MCP111/112

NOTES:

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- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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